



**DOCUMENT TITLE:
DS2433X FLIP CHIP PKG, 1.10MM PITCH PKG CODE BF623-3**

DOC ID # 21-0291 NEW REV: A

ECN#: HQ-08-5281 EFFECTIVE DATE: 07/16/08

ORIGINATOR: JEFF WALKER

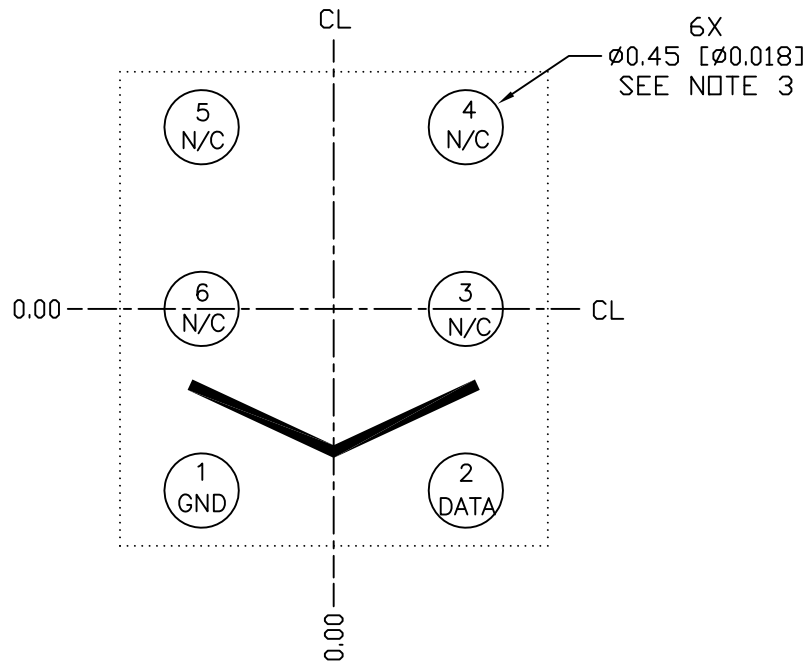
MOST RECENT CHANGES

FROM	TO
DALLAS DOCUMENT CONTROL SYSTEM DOC 56-G7022-001, REV B, LOGO-DALLAS/MAXIM	INITIAL RELEASE INTO MAXIM DOCUMENT CONTROL LOGO-MAXIM

NOTES:

1. DIMENSIONS: MM [INCH]
2. LASER MARK
3. LANDING PAD NOT DEFINED BY SOLDER MASK;
FOR PAD CONNECTIONS AND COORDINATES, SEE
TABLE 1
4. UNDERFILL RECOMMENDED FOR FR4 SUBSTRATE
APPLICATION

TABLE 1. LAND PAD CONNECTIONS AND CENTER COORDINATES					
		MILLIMETERS		INCHES	
NUMBER	NAME	X	Y	X	Y
1	GND	-0.80	-1.10	-0.031	-0.043
2	DATA	0.80	-1.10	0.031	-0.043
3	N/C	0.80	0.00	0.031	0.000
4	N/C	0.80	1.10	0.031	0.043
5	N/C	-0.80	1.10	-0.031	0.043
6	N/C	-0.80	0.00	-0.031	0.000



TOP SIDE

RECOMMENDED SUBSTRATE
LAND PATTERN

SIZE A	FSCM NO.	DWG NO. 21-0291	REV A
SCALE		SHEET 2 / 2	

REVISION HISTORY

REV	CHANGES MADE	DATE	INIT.
A	ECN# HQ-08-5281. INITIAL RELEASE INTO MAXIM DOCUMENT CONTROL. LOGO-MAXIM	07/16/08	JW



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